

THYRISTOR/ THYRISTOR

NEWADD-A-pak™ Power Modules

Features

- Electrically isolated: DBC base plate
- 3500 V_{RMS} isolating voltage
- Standard JEDEC package
- Simplified mechanical designs, rapid assembly
- Auxiliary cathode terminals for wiring convenience
- High surge capability
- Wide choice of circuit configurations
- Large creepage distances
- UL E78996 approved 

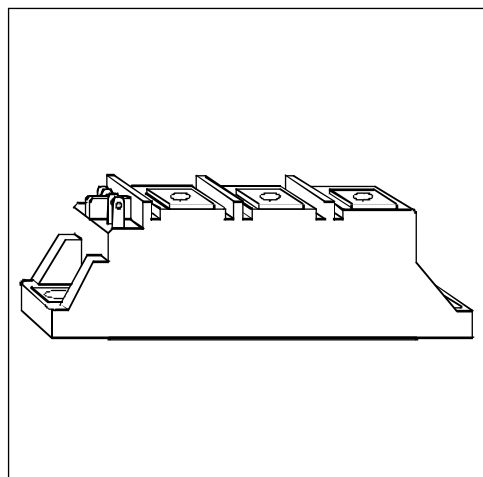
45 A
60 A

Description

These IRKU/V series of NEW ADD-A-paks use power thyristors in two circuit configurations. The semiconductor chips are electrically isolated from the base plate, allowing common heatsinks and compact assemblies to be built. They can be interconnected to form single phase bridges (IRKU+IRKV) or 6-pulse midpoint connection bridge. These modules are intended for general purpose high voltage applications such as high voltage regulated power supplies, battery charge and DC motor speed control circuits.

Major Ratings and Characteristics

Parameters	IRKU/V41	IRKU/V56	Units
$I_{T(AV)}$ @85°C	45	60	A
$I_{T(RMS)}$	70	95	A
I_{TSM} @50Hz	850	1310	A
@60Hz	890	1370	A
I^2t @50Hz	3.61	8.50	KA ² s
@60Hz	3.30	7.82	KA ² s
$I^2\sqrt{t}$	36.1	85.0	KA ² √s
V_{RRM} range	400to1600		V
T_{STG}	-40to125		°C
T_J	-40to125		°C



ELECTRICAL SPECIFICATIONS

Voltage Ratings

Type number	Voltage Code	V_{RRM} , maximum repetitive peak reverse voltage V	V_{RSM} , maximum non-repetitive peak reverse voltage V	V_{DRM} , max. repetitive peak off-state voltage, gate open circuit V	I_{RRM} , I_{DRM} 125°C mA
IRKU/V41, 56	04	400	500	400	15
	08	800	900	800	
	12	1200	1300	1200	
	16	1600	1700	1600	

On-state Conduction

Parameters	IRKU/V41	IRKU/V56	Units	Conditions		
$I_{T(AV)}$ Max. average on-state current	45	60	A	180° conduction, half sine wave, $T_C = 85^{\circ}\text{C}$		
$I_{T(RMS)}$ Max. RMS on-state current @ T_C	70	95		DC		
I_{TSM} Max. peak, one cycle non-repetitive on-state current	850	1310	A	t=10ms	No voltage	Sinusoidal half wave, Initial $T_J = T_J$ max.
	890	1370		t=8.3ms	reapplied	
	715	1100		t=10ms	100% V_{RRM}	
	750	1150		t=8.3ms	reapplied	
	940	1450		t=10ms	$T_J = 25^{\circ}\text{C}$,	
	985	1520		t=8.3ms	no voltage reapplied	
I^2t Max. I^2t for fusing	3.61	8.56	KA^2s	t=10ms	No voltage	Initial $T_J = T_J$ max.
	3.30	7.82		t=8.3ms	reapplied	
	2.56	6.05		t=10ms	100% V_{RRM}	
	2.33	5.53		t=8.3ms	reapplied	
	4.42	10.05		t=10ms	$T_J = 25^{\circ}\text{C}$,	
	4.03	9.60		t=8.3ms	no voltage reapplied	
$I^2\sqrt{t}$ Max. $I^2\sqrt{t}$ for fusing (1)	36.1	85.6	$\text{KA}^2\sqrt{\text{s}}$	$t=0.1$ to 10ms, no voltage reapplied		
$V_{T(TO)}$ Max. value of threshold voltage (2)	0.88	0.85	V	Low level (3)		$T_J = T_J$ max
	0.91	0.88		High level (4)		
r_t Max. value of on-state slope resistance (2)	5.90	3.53	mΩ	Low level (3)		$T_J = T_J$ max
	5.74	3.41		High level (4)		
V_{TM} Max. peak on-state voltage	1.81	1.54	V	$I_{TM} = \pi \times I_{T(AV)}$		$T_J = 25^{\circ}\text{C}$
				$I_{FM} = \pi \times I_{F(AV)}$		
di/dt Max. non-repetitive rate of rise of turned on current	150		A/μs	$T_J = 25^{\circ}\text{C}$, from 0.67 V_{DRM} , $I_{TM} = \pi \times I_{T(AV)}$, $I_g = 500\text{mA}$, $t_r < 0.5 \mu\text{s}$, $t_p > 6 \mu\text{s}$		
I_H Max. holding current	200		mA	$T_J = 25^{\circ}\text{C}$, anode supply = 6V, resistive load, gate open circuit		
I_L Max. latching current	400			$T_J = 25^{\circ}\text{C}$, anode supply = 6V, resistive load		

(1) I^2t for time $t_X = I^2\sqrt{t} \times \sqrt{t_X}$.(2) Average power = $V_{T(TO)} \times I_{T(AV)} + r_t \times (I_{T(RMS)})^2$ (3) $16.7\% \times \pi \times I_{AV} < I < \pi \times I_{AV}$ (4) $I > \pi \times I_{AV}$

Triggering

Parameters		IRKU/V41	IRKU/V56	Units	Conditions	
P _{GM}	Max. peak gate power	10	10	W		
P _{G(AV)}	Max. average gate power	2.5	2.5			
I _{GM}	Max. peak gate current	2.5	2.5	A		
-V _{GM}	Max. peak negative gate voltage	10		V	Anode supply = 6V resistive load	
V _{GT}	Max. gate voltage required to trigger	4.0				
		2.5				
		1.7				
I _{GT}	Max. gate current required to trigger	270		mA	T _J = - 40°C	Anode supply = 6V resistive load
		150			T _J = 25°C	
		80			T _J = 125°C	
V _{GD}	Max. gate voltage that will not trigger	0.25		V	T _J = 125°C, rated V _{DRM} applied	
I _{GD}	Max. gate current that will not trigger	6		mA	T _J = 125°C, rated V _{DRM} applied	

Blocking

Parameters	IRKU/V41, 56	Units	Conditions
I_{RRM} Max. peak reverse and off-state leakage current at V_{RRM} , V_{DRM}	15	mA	$T_J = 125^\circ\text{C}$, gate open circuit
V_{INS} RMS isolation voltage	2500 (1 min) 3500 (1 sec)	V	50 Hz, circuit to base, all terminals shorted
dv/dt Max. critical rate of rise of off-state voltage (5)	500	V/ μs	$T_J = 125^\circ\text{C}$, linear to 0.67 V_{DRM} , gate open circuit

Thermal and Mechanical Specifications

Parameters		IRKU/V41	IRKU/V56	Units	Conditions
T _J	Junction operating temperature range	- 40 to 125		°C	
T _{stg}	Storage temper. range				
R _{thJC}	Max. internal thermal resistance, junction to case	0.23	0.20	K/W	Per module, DC operation
R _{thCS}	Typical thermal resistance case to heatsink	0.1			Mountingsurfaceflat, smoothandgreased. Flatness < 0.03 mm; roughness< 0.02 mm
T	Mounting torque ± 10% to heatsink busbar	5		Nm	A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound
		3			
wt	Approximate weight	83 (3)		g (oz)	
Case style		TO-240AA		JEDEC	

(5) Available with $dv/dt = 1000\text{V}/\mu\text{s}$, to complete code add S90 i.e. IRKU41/16S90.

IRKU/V41, 56 Series

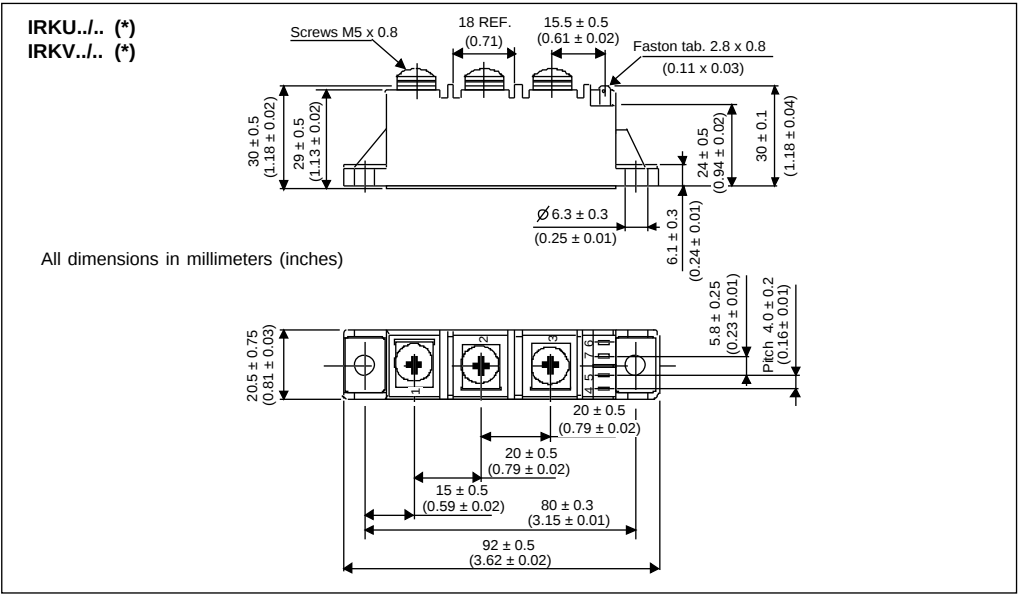
Bulletin I27134 rev. B 09/97

ΔR Conduction (per Junction)

(The following table shows the increment of thermal resistance R_{thJC} when devices operate at different conduction angles than DC)

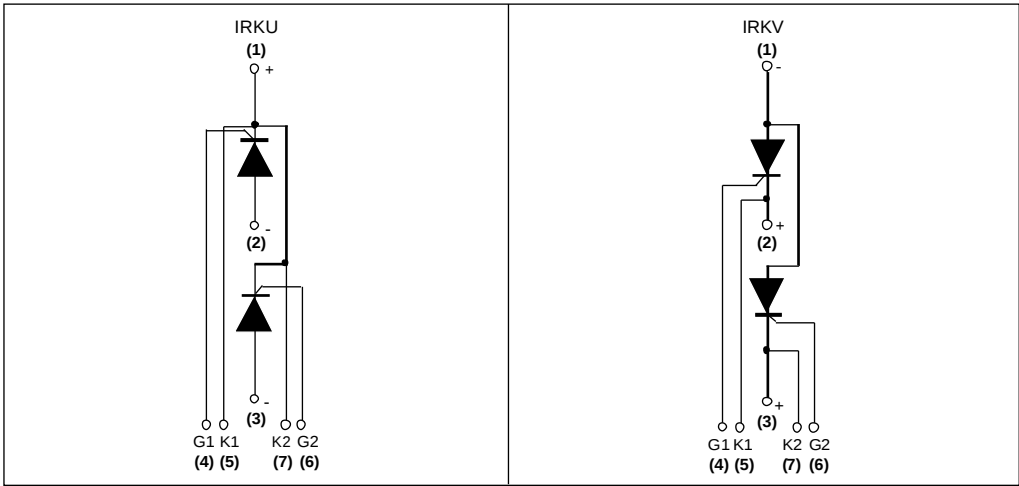
Devices	Sine half wave conduction					Rect. wave conduction					Units
	180°	120°	90°	60°	30°	180°	120°	90°	60°	30°	
IRKU/V41	0.11	0.13	0.17	0.23	0.34	0.09	0.14	0.18	0.23	0.34	°C/W
IRKU/V56	0.09	0.11	0.13	0.18	0.27	0.07	0.11	0.14	0.19	0.28	

Outlines Table



(*) For terminals connections, see Circuit Configurations Table

Circuit Configurations Table



NOTE: To order the Optional Hardware see Bulletin I27900

Ordering Information Table

Device Code				
IRK	U	56	/	16 S90
①	②	③	④	⑤
1	- Module type			
2	- Circuit configuration (See Circuit Configuration Table)			
3	- Current code			
4	- Voltage code (See Voltage Ratings Table)			
5	- dv/dt code: S90 = dv/dt 1000 V/μs No letter = dv/dt 500 V/μs			

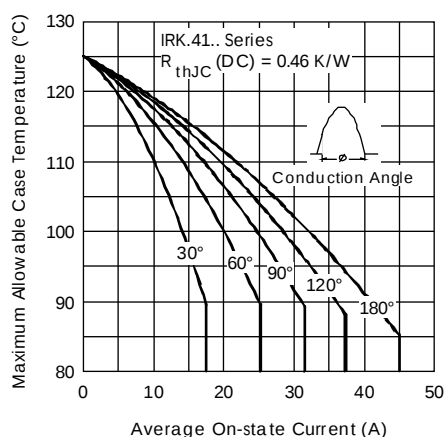


Fig. 1 - Current Ratings Characteristics

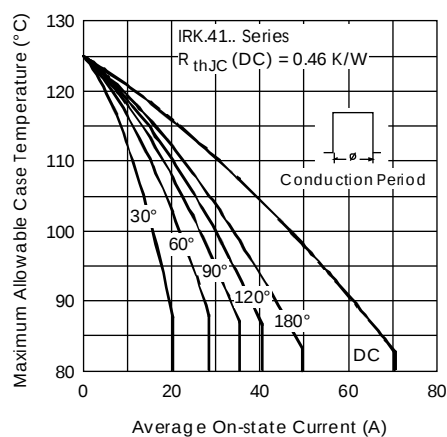


Fig. 2 - Current Ratings Characteristics

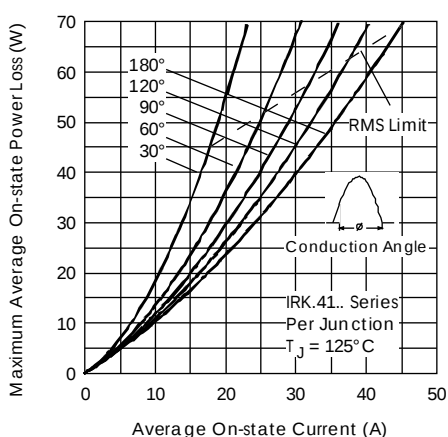


Fig. 3 - On-state Power Loss Characteristics

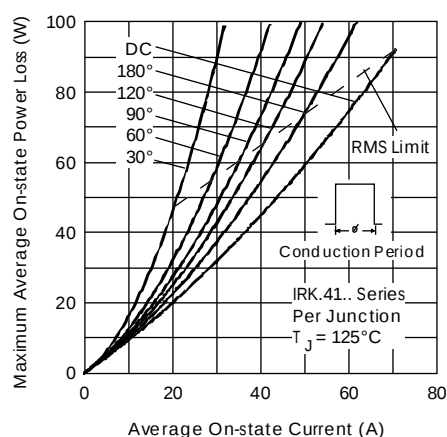


Fig. 4 - On-state Power Loss Characteristics

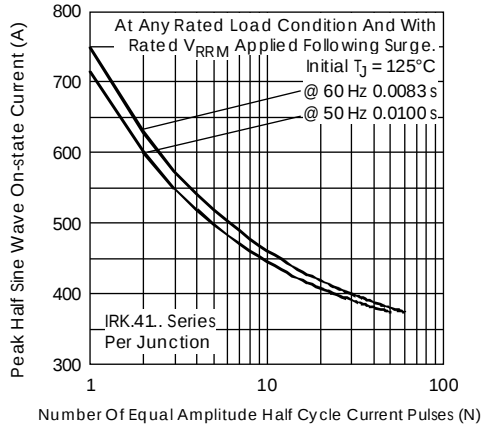


Fig. 5 - Maximum Non-Repetitive Surge Current

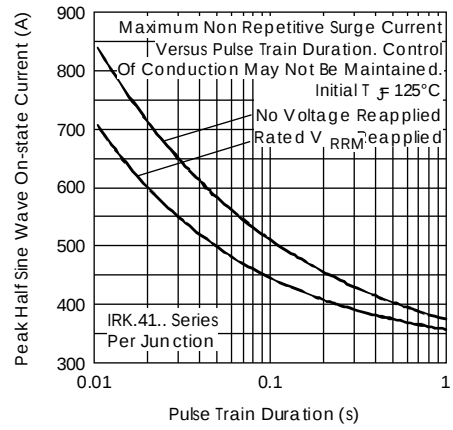


Fig. 6 - Maximum Non-Repetitive Surge Current

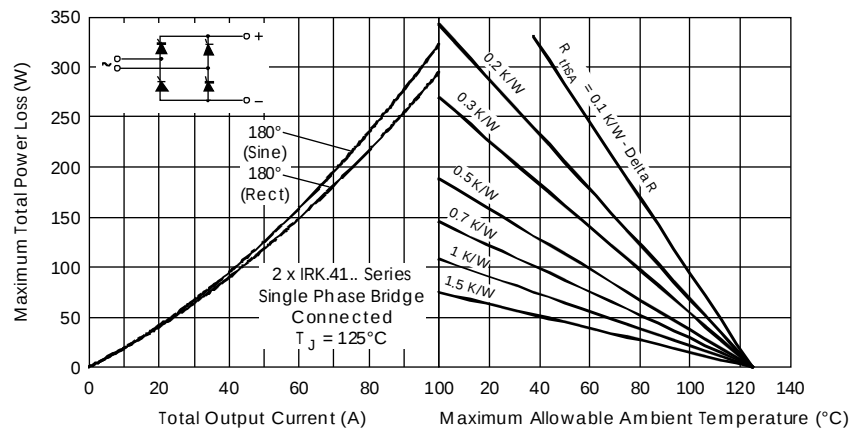


Fig. 7 - On-state Power Loss Characteristics (Single Phase Bridge IRKU+IRKV)

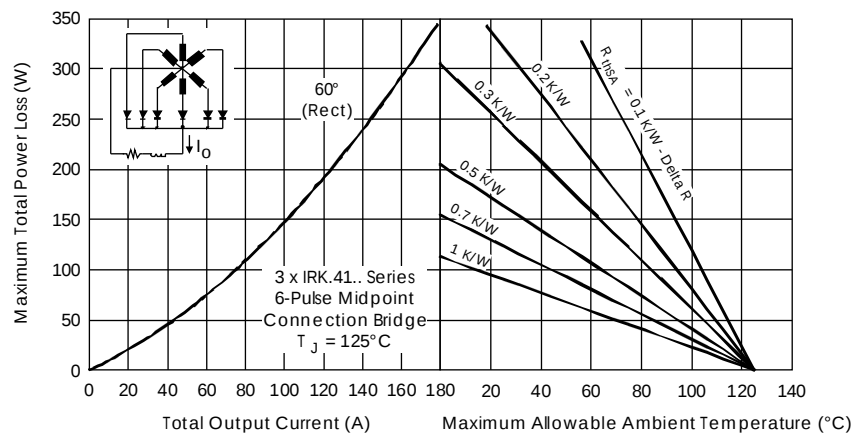


Fig. 8 - On-state Power Loss Characteristics

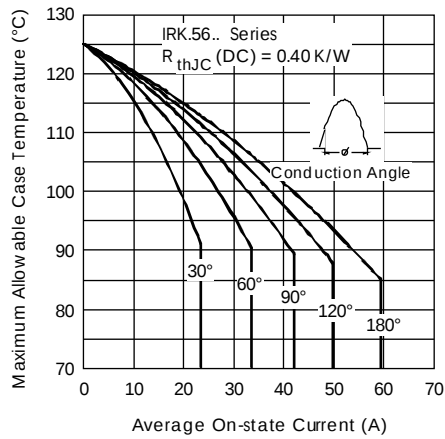


Fig. 9 - Current Ratings Characteristics

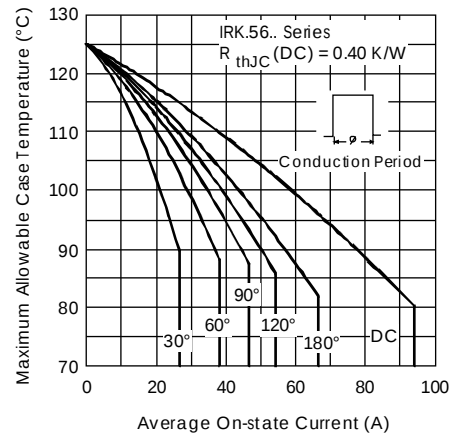


Fig. 10 - Current Ratings Characteristics

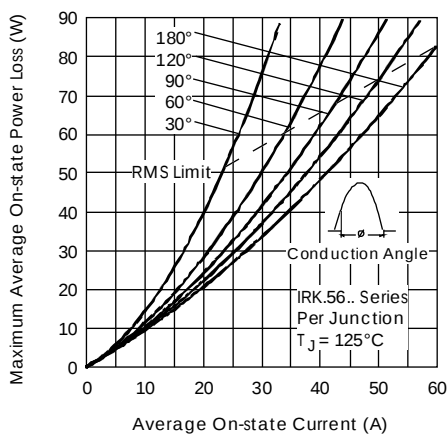


Fig. 11 - On-state Power Loss Characteristics

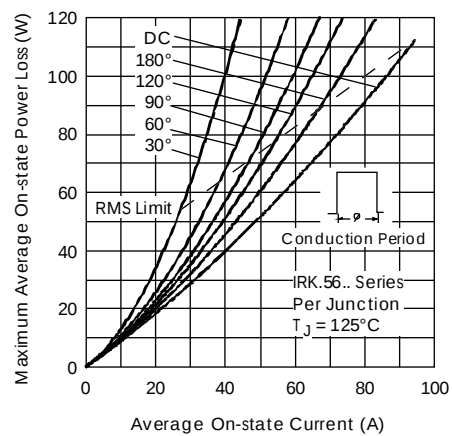


Fig. 12 - On-state Power Loss Characteristics

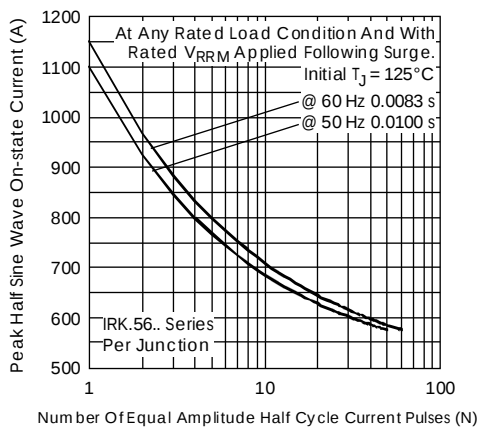


Fig. 13 - Maximum Non-Repetitive Surge Current

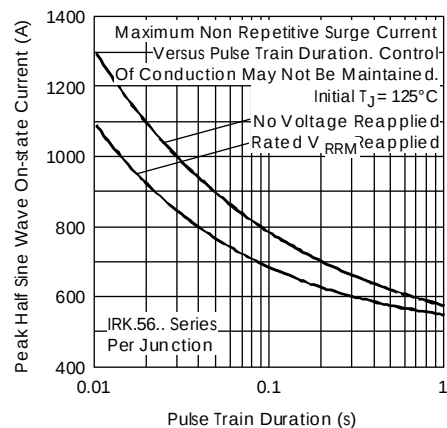


Fig. 14 - Maximum Non-Repetitive Surge Current

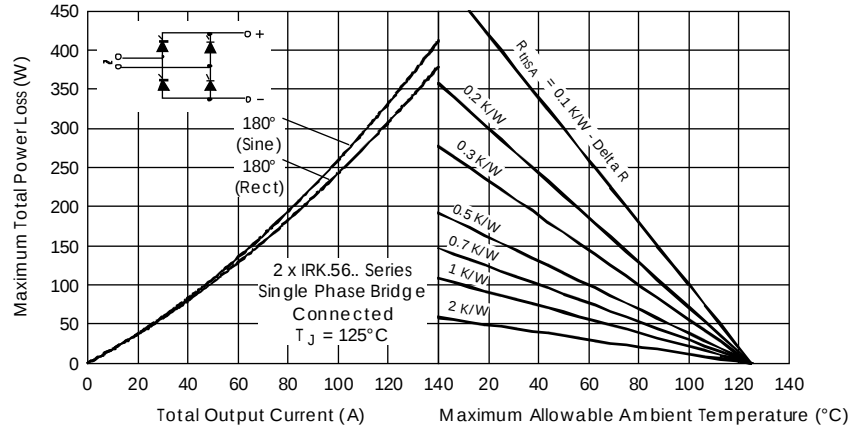


Fig. 15 - On-state Power Loss Characteristics (Single Phase Bridge IRKU+IRKV)

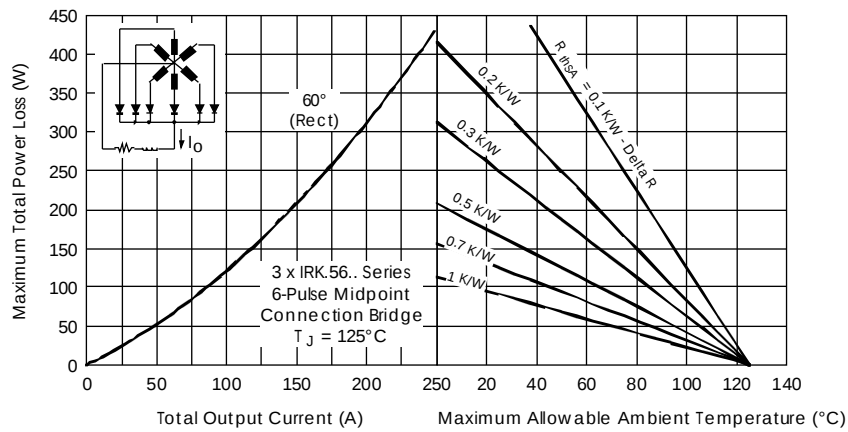


Fig. 16 - On-state Power Loss Characteristics

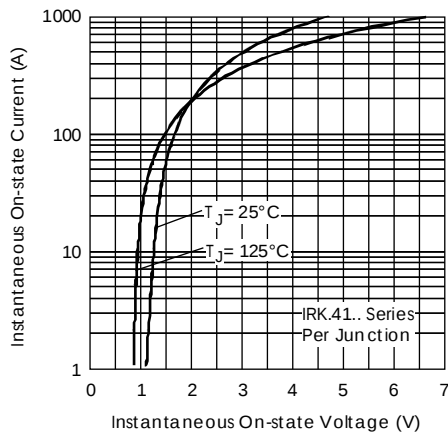


Fig. 17 - On-state Voltage Drop Characteristics

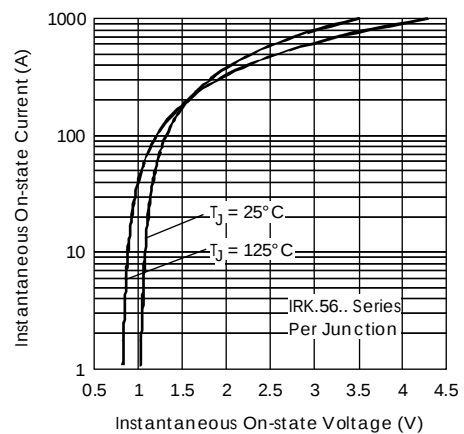


Fig. 18 - On-state Voltage Drop Characteristics

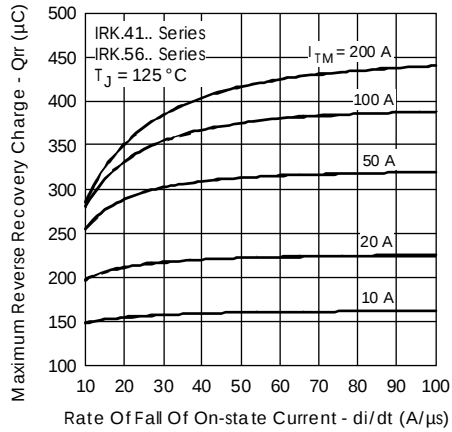


Fig. 19 - Recovery Charge Characteristics

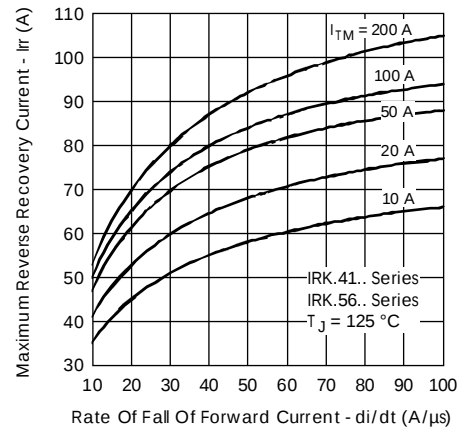


Fig. 20 - Recovery Current Characteristics

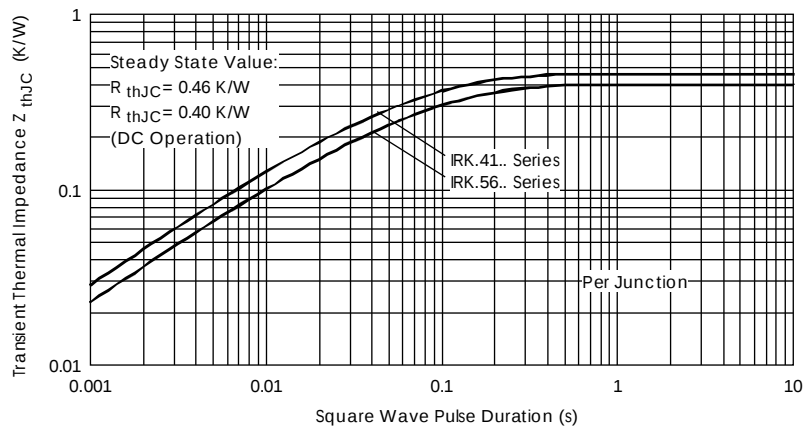


Fig. 21 - Thermal Impedance Z_{thJC} Characteristics

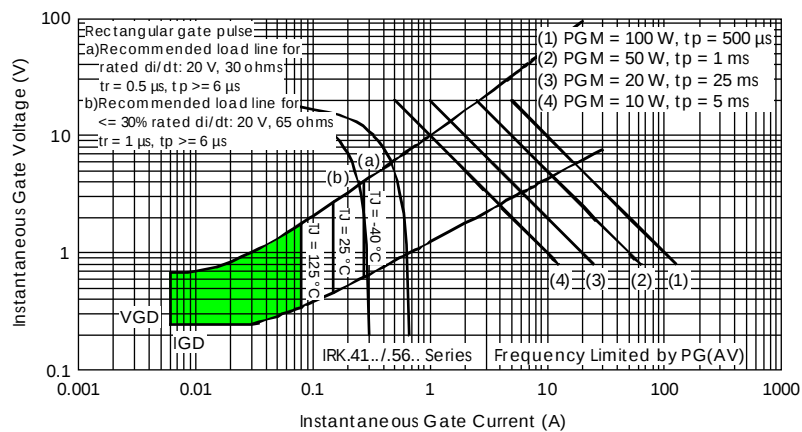


Fig. 22 - Gate Characteristics